DBQ, DGV, DW, OR PW PACKAGE (TOP VIEW)

10E

1B1

1A1 Π

1A2

1B2 | I

1B3 [

1A3 [

1A4 ∏

1B4

1A5

GND

1B5 | 10

3

6

8

9

11

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24 🛮 V_{CC}

22 2A5

21 2A4

20 2B4

19 □ 2B3

18 2A3

16 2B2

15 2B1

14 2A1

2OE

13

23 2B5

- 5-Ω Switch Connection Between Two Ports
- Rail-to-Rail Switching on Data I/O Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

description/ordering information

The SN74CBTLV3384 provides ten bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as dual 5-bit bus switches with separate output-enable (\overline{OE}) inputs. It can be

used as two 5-bit bus switches or one 10-bit bus switch. When \overline{OE} is low, the associated 5-bit bus switch is on, and A port is connected to B port. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, \overline{OE} shall be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	QSOP – DBQ	Tape and reel	SN74CBTLV3384DBQR	CBTLV3384	
–40°C to 85°C	0010 5111	Tube	SN74CBTLV3384DW	ODTI \ /0004	
	SOIC - DW	Tape and reel	SN74CBTLV3384DWR	CBTLV3384	
	TSSOP - PW	Tape and reel	SN74CBTLV3384PWR	CL384	
	TVSOP - DGV	Tape and reel	SN74CBTLV3384DGVR	CL384	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each 5-bit bus switch)

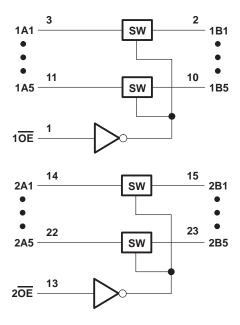
INPUTS		INPUTS/OUTPUTS		
10E	2OE	1B1-1B5	2B1-2B5	
L	L	1A1-1A5	2A1-2A5	
L	Н	1A1-1A5	Z	
Н	L	Z	2A1-2A5	
Н	Н	Z	Z	



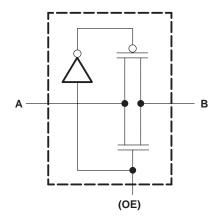
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logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Continuous channel current		28 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)		50 mA
Package thermal impedance, θ _{JA} (see Note 2)): DBQ package 6	1°C/W
	DGV package 8	6°C/W
	DW package 4	6°C/W
	PW package 8	8°C/W
Storage temperature range, T _{stg}	–65°C to	150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	V _{CC} Supply voltage			3.6	V
.,	High level control to not voltone	V _{CC} = 2.3 V to 2.7 V	1.7		
V _{IH} High-le	h-level control input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
.,	Law law al accepted in most violations	V _{CC} = 2.3 V to 2.7 V		0.7	
VIL	Low-level control input voltage $V_{CC} = 2.7 \text{ V t}$			0.8	٧
TA	Operating free-air temperature		-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER		TEST CONDITI	ONS	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 3 V,	$I_{\parallel} = -18 \text{ mA}$				-1.2	V
l _l		$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND				±1	μΑ
l _{off}		$V_{CC} = 0$,	V_{I} or $V_{O} = 0$ to 3.6 V	,			10	μΑ
Icc		$V_{CC} = 3.6 \text{ V},$	I _O = 0,	$V_I = V_{CC}$ or GND			10	μΑ
∆lcc [‡]	Control inputs	$V_{CC} = 3.6 \text{ V},$	One input at 3 V,	Other inputs at V _{CC} or GND			300	μΑ
Ci	Control inputs	V _I = 3 V or 0				4.5		pF
C _{io(OFI}	F)	$V_0 = 3 \text{ V or } 0,$	OE = V _{CC}			10		pF
		.,	V _I = 0	I _I = 64 mA		5	8	
		$V_{CC} = 2.3 \text{ V},$ TYP at $V_{CC} = 2.5 \text{ V}$		I _I = 24 mA		5	8	
r _{on} §		111 at vCC = 2.5 v	V _I = 1.7 V,	I _I = 15 mA		27	40	Ω
lou ₂				I _I = 64 mA		5	7	22
		V _{CC} = 3 V	V _I = 0	I _I = 24 mA		5	7	
			V _I = 2.4 V,	I _I = 15 mA		10	15	

[†] All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INPUT)		MIN	MAX	MIN	MAX	i
$t_{pd}\P$	A or B	B or A		0.15		0.25	ns
t _{en}	ŌE	A or B	1	5	1	4.3	ns
^t dis	ŌĒ	A or B	1	5.5	1	5.5	ns

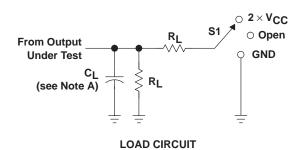
The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[‡] This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND.

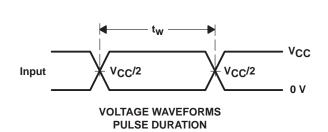
[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

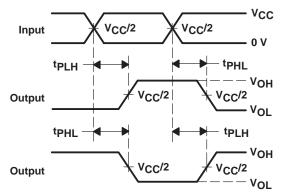
PARAMETER MEASUREMENT INFORMATION



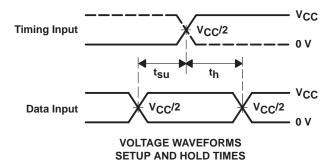
TEST	S1
tPLH/tPHL	Open
t _{PLZ} /t _{PZL}	2×V _{CC}
tPHZ/tPZH	GND

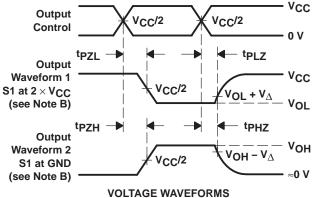
VCC	CL	RL	$v_{\scriptscriptstyle\Delta}$
2.5 V ±0.2 V	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	50 pF	500 Ω	0.3 V





VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES **INVERTING AND NONINVERTING OUTPUTS**





ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns. $t_f \leq 2$ ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpZL and tpZH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



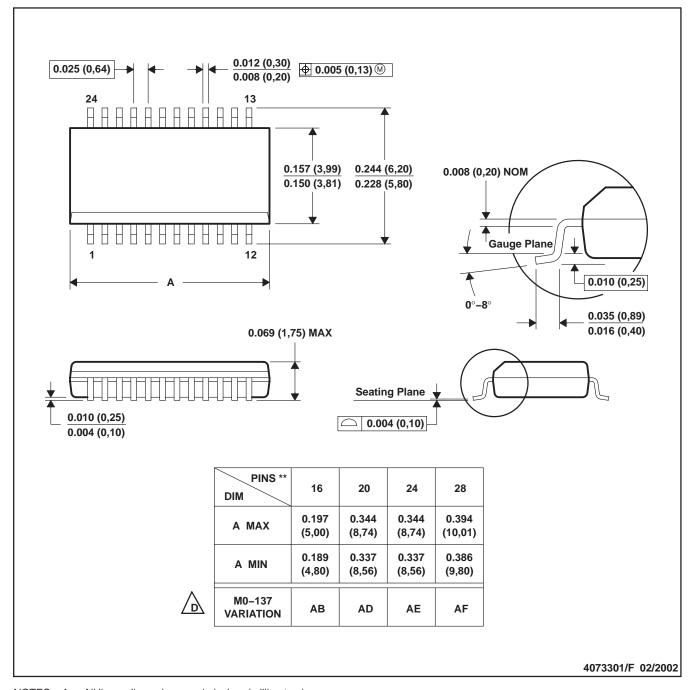
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DBQ (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-137.

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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